



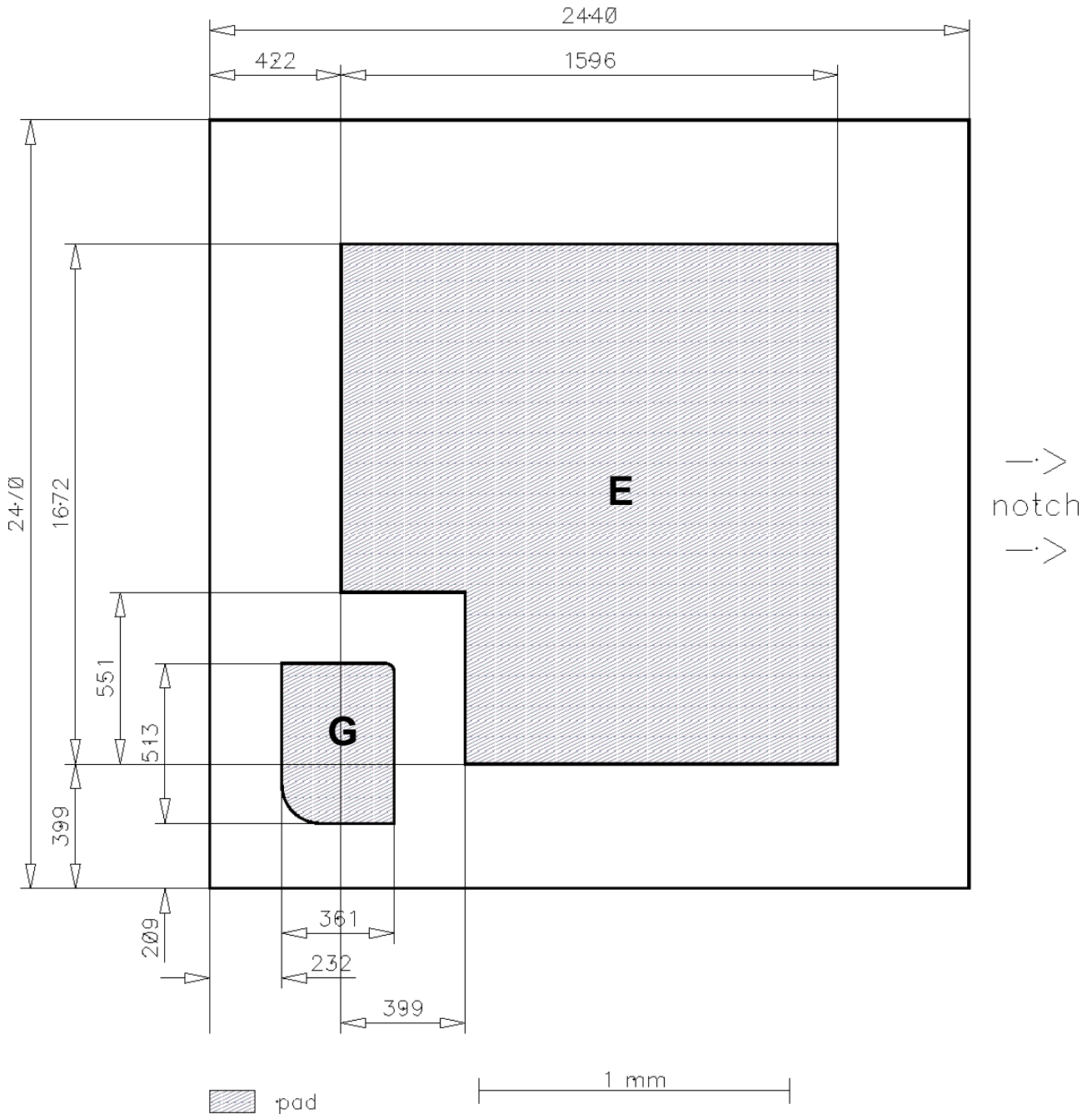
### **Further Electrical Characteristic**

Switching characteristics and thermal properties are depending strongly on package design and mounting technology and can therefore not be specified for a bare die.

Further technical information about the performance of this chip in package t.b.d. is given exemplarily at [www.infineon.com/igbt](http://www.infineon.com/igbt). The chip qualification is independent of the qualification which is performed for the Discretes.

Chip Drawing

Die-Size 2440 μm x 2470 μm



**E** = Emitter

**G** = Gate